

# **Asia Pacific Flip Chip Market By Packaging Technology (2.5D IC, 3D IC, and 2D IC), By Bumping Technology (Copper Pillar, Gold Bumping, Solder Bumping and Others), By End User (Electronics, Industrial, IT & Telecom, Automotive, Healthcare & Life Sciences, Aerospace & Defense and Others), By Country, Industry Analysis and Forecast, 2020 - 2026**

<https://marketpublishers.com/r/A1C78852034BEN.html>

Date: July 2020

Pages: 107

Price: US\$ 1,500.00 (Single User License)

ID: A1C78852034BEN

## **Abstracts**

The Asia Pacific Flip Chip Market would witness market growth of 8.6% CAGR during the forecast period (2020-2026).

Flip chip has a promising ability as packaging technology to shift the scenario of traditional electrical interconnection solutions. The fundamental properties of flip chip make it a potential interconnecting packaging technology for various industries. Flip chip is one of the most researched packaging innovations for electrical interconnections because of its ability to alter the current packaging market landscape.

It provides a range of advantages, such as smaller IC footprint, reduced size, increased performance, superior reliability and thermal capability for mobile devices such as smartphones, digital cameras & cameras, and laptops & tablets. The copper pillar segment is projected to see the fastest growth leading to decreased pitch, improved performance and cost-effectiveness. 3D IC packaging is expected to have a significant market share in the near future due to an increase in the application of 3D IC to miniature consumer electronics.

Flip chip has a promising potential of IoT owing to its wide variety of applications in consumer electronics, automotive & transport, industrial, healthcare, aerospace &

defense and renewable energy infrastructure. The Internet of Things (IoT) is the main driving force of the flip chip market, owing to high performance, small packaging size, and hybrid integration capacity of flip chips. The growth of the flip chip industry is largely driven by the evolving concept of IOT, a network of physical machines, cars, houses, and others, including embedded electronics, software, sensors, actuators, and network connectivity.

Based on Packaging Technology, the market is segmented into 2.5D IC, 3D IC and 2D IC. Based on Bumping Technology, the market is segmented into Copper Pillar, Gold Bumping, Solder Bumping and Others. Based on End User, the market is segmented into Electronics, Industrial, IT & Telecom, Automotive, Healthcare & Life Sciences, Aerospace & Defense and Others. Based on countries, the market is segmented into China, Japan, India, South Korea, Singapore, Malaysia, and Rest of Asia Pacific.

The market research report covers the analysis of key stake holders of the market. Key companies profiled in the report include 3M Company, Advanced Micro Devices, Inc., Amkor Technology, Inc., Apple, Inc., Fujitsu Limited, Intel Corporation, IBM Corporation, Samsung Electronics Co., Ltd., Texas Instruments, Inc., and Taiwan Semiconductor Manufacturing Company.

## Scope of the Study

## Market Segmentation:

### By Packaging Technology

2.5D IC

3D IC

2D IC

### By Bumping Technology

Copper Pillar

Gold Bumping

Solder Bumping

Others

#### By End User

Electronics

Industrial

IT & Telecom

Automotive

Healthcare & Life Sciences

Aerospace & Defense

Others

#### By Country

China

Japan

India

South Korea

Singapore

Malaysia

Rest of Asia Pacific

## Companies Profiled

3M Company

Advanced Micro Devices, Inc.

Amkor Technology, Inc.

Apple, Inc.

Fujitsu Limited

Intel Corporation

IBM Corporation

Samsung Electronics Co., Ltd.

Texas Instruments, Inc.

Taiwan Semiconductor Manufacturing Company

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